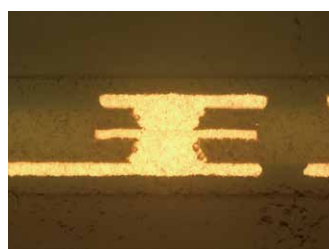


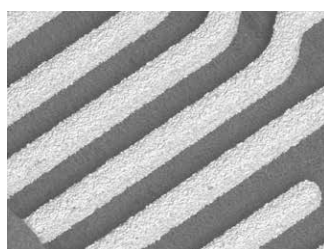
ベトナム第三工場 ロードマップ

Contents		Technology Roadmap (Unit: μm)		
		FY 2025	FY 2026	FY 2027
L/S Line Width/Space	Tenting (Cu thickness $13\mu\text{m}$)	25/30	←	←
	MSAP (Cu thickness $13\mu\text{m}$)	20/20	15/20	15/15
WB Pad Width/Space	Tenting (Cu thickness $13\mu\text{m}$)	70	←	←
	MSAP (Cu thickness $13\mu\text{m}$)	55	50	←
Laser Via Pitch/ via Size/Pad Diameter (Annular Ring)		160/60/120 (30)	140/50/100 (25)	120/40/80 (20)
Mechanical Via Size/Pad Diameter (Annular Ring)		100/200 (50)	80/180 (50)	←
Core Thickness		40	←	←
PP Thickness		20	15	←
Copper thickness		13	10	←
Coreless	Availability	○	←	←
Solder Resist	Thickness	13	←	←
	SRO Size	100	80	←
	SRR	20	15	←
	Flatness	5	←	←
	Method	Ink/DFSR	←	←
Surface Finish	Au Plating	Soft/Hard Gold, ENEPIG	←	←
	OSP	Shikoku: F2LX (PK)	←	←
Front and back misalignment		25	20	←
Total Thickness		Cored (2L) 90 Coreless (3L) 106	Cored (2L) 85 Coreless (3L) 85	←
Strip Size (Small Strip)		Min 25mm	←	←
Process		STD/EB/EBS	←	←

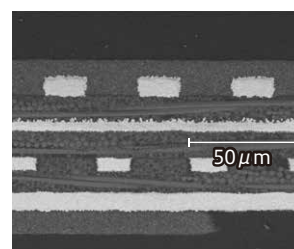
高精細パターン形成 High definition pattern formation



3L coreless



L/S = 20/20 μm



L/S = 25/25 μm